Package PLCC44

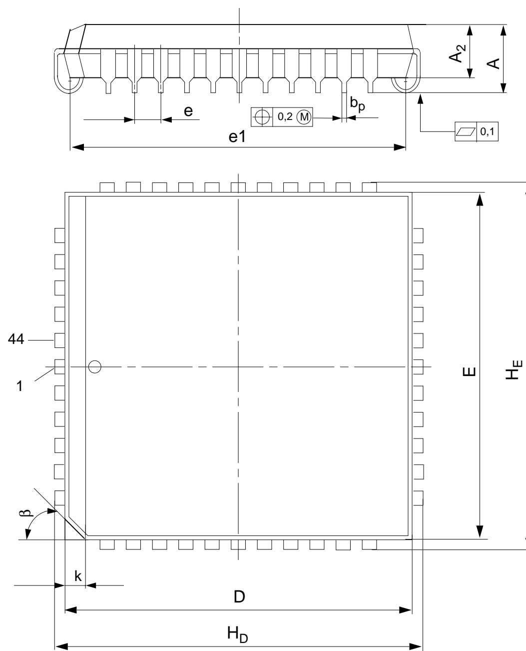
MDS 723

Supersedes Edition 03.94

Dimensions in millimetres

Based on IEC 191-2Q: Type 112E10

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	4,60
b_{Pmin}	0,33
b_{Pmax}	0,53
e_{nom}	1,27
H_{Dmin}	17,40
H_{Dmax}	17,65
H_{Emin}	17,40
H_{Emax}	17,65

Dimensions of Sub-Group C1	
A_{min}	4,15
A_{2min}	3,10
A_{2max}	3,96
D_{min}*	16,50
D_{max}*	16,70
E_{min}*	16,50
E_{max}*	16,70
k_{min}	1,00
β	45°
$e1_{min}$	15,00
$e1_{max}$	16,00

* without mold-flash

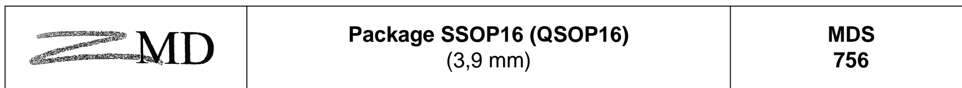
2 Weight ≤ 2,4 g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form J-bends



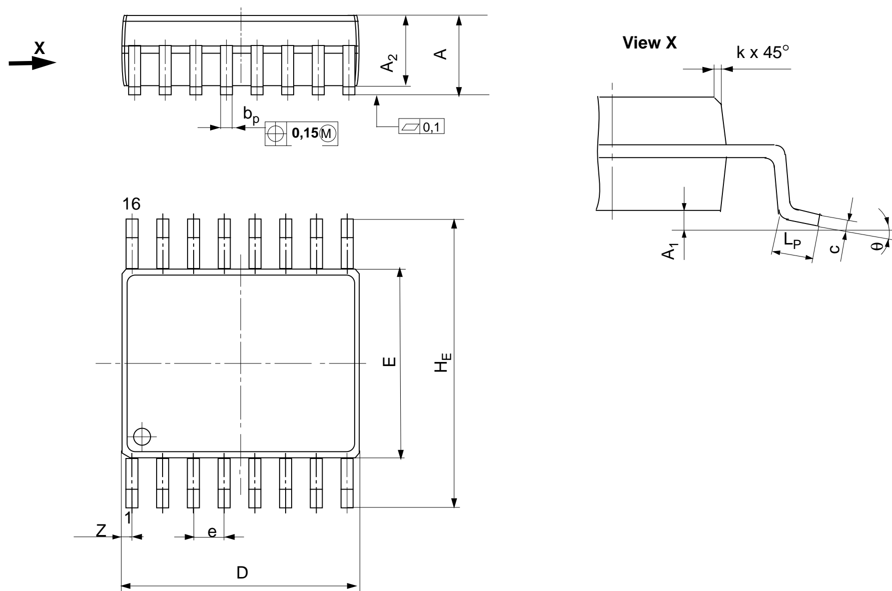
Package SSOP16 (QSOP16) (3,9 mm)

MDS 756

Dimensions in millimetres

Based on JEDEC JEP95: MO-137

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	1,73
b_{Pmin}	0,20
b_{Pmax}	0,30
e_{nom}	0,635
H_{Emin}	5,90
H_{Emax}	6,14
L_{Pmin}	0,41
Z_{max}	0,27

Dimensions of Sub-Group C1	
A_{min}	1,54
A_{1min}	0,10
A_{1max}	0,25
A_{2min}	1,40
A_{2max}	1,55
c_{min}	0,18
c_{max}	0,25
D_{min}*	4,80
D_{max}*	4,98
E_{min}*	3,82
E_{max}*	4,00
k_{min}	0,25
θ_{min}	0°
θ_{max}	8°

* without mold-flash

2 Weight ≤ 0,4 g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form Z-bends

Zentrum Mikroelektronik Dresden		
Editor:	Date:	Doc-No. QS-000756-HD-01
Check:	Quality:	

Package SOP8 (SO8) (150 mil)

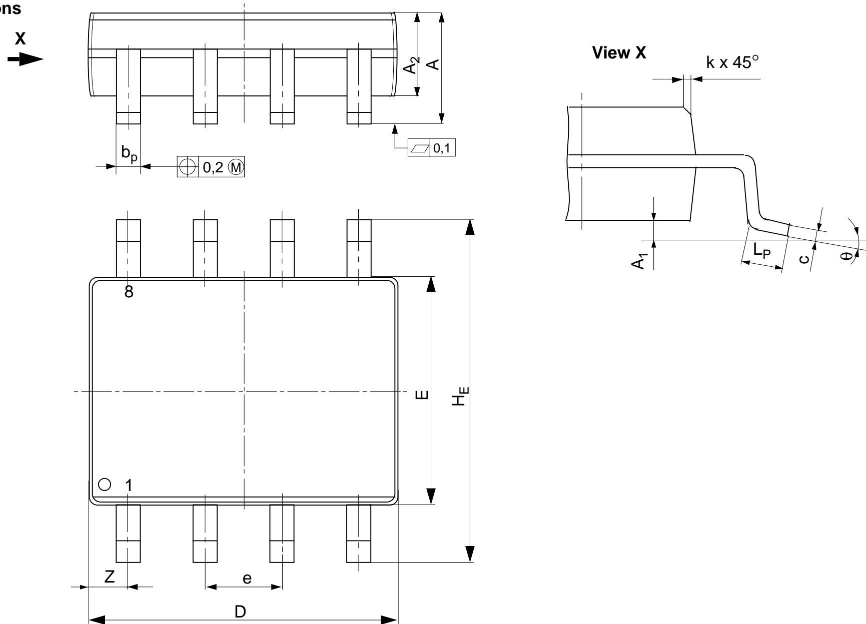
MDS 726

Supersedes
Edition 01.95

Dimensions in millimetres

Based on IEC 191-2Q: Type 076E35 B

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	1,95
b_{Pmin}	0,35
b_{Pmax}	0,49
e_{nom}	1,27
H_{Emin}	5,80
H_{Emax}	6,30
L_{Pmin}	0,40
Z_{max}	0,635

Dimensions of Sub-Group C1	
A_{min}	1,55
A_{1min}	0,10
A_{1max}	0,30
A_{2min}	1,40
A_{2max}	1,80
c_{min}	0,15
c_{max}	0,25
D_{min}*	4,80
D_{max}*	5,00
E_{min}*	3,80
E_{max}*	4,00
k_{min}	0,25
θ_{min}	0°
θ_{max}	8°

* without mold-flash

2 Weight ≤ 0,3 g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form Z-bends